

Capabilité Usine



	Items	Capability (Unit:mm)
1	Min Board thickness	0.2
2	V-CUT Min Board thickness	0.4
3	machine V-CUT Size	80-380
4	Min width/space (0.5OZ)	0.08/0.08
5	width/space (1OZ)	0.10/0.10
6	Copper	HOZ-6OZ
7	griddingin width/space	0.2/0.2
8	the min space from copper to outline (including PTH hole and NPTH )	0. 2
9	The min space from inter hole to the nonconnected copper	0. 15MM (4L)
		0. 18MM (6L)
		0. 2MM (8L)
		0. 23MM (Above 10L)
10	Inter layer annulay ring	≥0. 12 (above 4L)
11	Min thickness	0.2(2L)
		0.4(4L)
		0.6(6L)
		0.8 (8L)
		1.0 (10L)
12	layer	1-30 L
13	Min PTH	0.45
14	Min NPTH Milling hole	0.8
15	Min drilling	0.1
16	hole wall copper	0.018~0.035
17	PTH tolerance	±0.075MM ±0.05MM
18	NPTH tolerance	±0.05
19	outer (or double sided) plug hole ring	≥0. 18
20	The minimum green oil bridge 0.1	
21	Min legend thickness and legend thickwire	0.8/0.15mm
22	The minimum insulation resistance	10(22)Ω
23	The stripping strength	≤1.1N/ mm
24	On-off test voltage	50~300V
25	Warp and Twist	≤0.075%
26	hole position tolerance	±0.05
27	Protile Dimensiontolerance	±0.13
28	Panel size	400×600
29	impedance control	±10% OHM
30	via in pad	0.15
31	Carb on ink	
32	Peela ble Mask	
33	ENIG+OSP S	older ENIG,and the BGA make OSP
34	Half Metal package edge	finish hole :0.5MM
35	Countersunk hole,ladder hole	±0.2MM